



# Terepac expands footprint to Silicon Valley

## Printable electronics player accepted into incubator

Waterloo ON-based pioneers in printable miniaturized electronics, Terepac Corp., is now transitioning from R&D into pilot line production after being accepted into the Plug and Play Tech Center in Sunnyvale CA, an incubator in the heart of Silicon Valley.

Terepac's proprietary process enables sophisticated microelectronics to be printed on flexible substrates at a fraction of the size from conventional methods - down to submicron scale - less than one one-thousandths of a millimeter - with nanometer precision and at a cost far lower than that of creating conventional rigid circuits. Entire devices with microprocessors,

memory and sensors can be reduced to less than a millimeter square, thinner than paper, and flexible enough to bend around a pencil - with no sacrifice in performance.

Because the size, weight and rigidity of the underlying electronics often determines the form of an end product, Terepac's breakthroughs enables existing electronic devices to be delivered in order of magnitude smaller (and flexible) form factors when compared to today's offerings. In addition, Terepac enables electronics to be cost-effectively embedded into a range of objects and devices, transforming them into smart objects. Given the rise in smart phones, mobile phones,

geolocation and the burgeoning Internet of Things, the ability to enable objects to report on their location or condition, as well as to communicate, interact and transact with users, will become increasingly valuable.

Founded in 2004, the company's investors include John Thompson, (former vice chairman of IBM Worldwide) and John Pollock (former chairman and CEO Electrohome Ltd.) while its technical advisors include Dr. Joel Birnbaum (former chief scientist of Hewlett-Packard, and former director of HP Labs), and Dr. Yoshio Nishi (former SVP and director of R&D of Texas Instruments' Semiconductor).